



ILLINOIS SOCIETY OF PROFESSIONAL ENGINEERS
Incorporated

ROCKFORD CHAPTER

MEMO

DATE: January 28, 2010
TO: High School Seniors
FROM: ISPE – Rockford Chapter
RE: Engineering Scholarships

\$4,000 ENGINEERING SCHOLARSHIP OPPORTUNITY

The Rockford Chapter of the Illinois Society of Professional Engineers will be offering an engineering scholarship to a high school senior from within our chapter boundaries. The scholarship applicant should complete the attached ISPE Rockford Chapter Scholarship Application form. All applications received will be eligible for local chapter scholarship consideration only, due to the fact that ISPE has decided not to participate in the state and national levels.

It is with great pride that our local Chapter offers the most significant scholarship opportunity. The recipient of the ISPE Rockford Chapter engineering scholarship will receive \$1,000/year for four years. The eligibility requirements for the scholarship are as those identified on the Scholarship Application forms. The scholarship recipient will be required to document that eligibility requirements are met each year prior to receiving payment.

To be given consideration for the scholarship, applicants should return the application forms with supporting documentation by March 15, 2010 to:

Jeffrey A. Bockhop, P.E.
Stenstrom General Contractor – Design/Build Group
P. O. Box 5866
Rockford, IL 61125
(815) 398-2420

The winner shall be notified approximately April 1, 2010.



The Rockford Chapter of Illinois Society of Professional Engineers
Announces
Engineering Scholarship Available to
Graduating High School Seniors
2009 - 2010

ALL SCHOLARSHIPS ARE CONTINGENT UPON RECIPIENT'S ENROLLMENT AND ACCEPTANCE IN AN ENGINEERING PROGRAM ACCREDITED BY THE ENGINEERING ACCREDITATION BOARD FOR ENGINEERING AND TECHNOLOGY (ABET). RECIPIENTS MAY ATTEND THE COLLEGE OR UNIVERSITY OF THEIR CHOICE PROVIDED THE ENGINEERING CURRICULUM SELECTED MEETS THE ABET-ACCREDITATION PROVISION STATED ABOVE.

ISPE – Rockford Chapter \$1,000 per year for four years

Made possible through donations and projects sponsored by the Rockford Chapter of ISPE. This scholarship is awarded to a single high school senior, within the boundaries of the Rockford Chapter of the Illinois Society of Professional Engineers, who plans to pursue a degree in engineering.

The recipient of this scholarship must abide by either set of the following rules:

- A. Initial enrollment in an engineering program:
1. Enrollment in an engineering program at an ABET accredited college or university.
 2. A grade point of 3.0 based on a 4.0 point system must be maintained. If your grade point falls short, the money will be held back until the required grade point average is restored.
 3. After each fall semester submit an official school transcript of your grades to verify eligibility.
 4. The Scholarship Check will be issued to you upon successful completion of items 1 through 3.
 5. If any of the above rules are not met, then the scholarship will be forfeited.
- B. Start at a community college then transfer to an engineering college:
1. After completion at a community college then transfer to an engineering program at an ABET accredited college or university.
 2. A grade point of 3.0 based on a 4.0 point system must be maintained. If your grade point falls short, the money will be held back until the required grade point average is restored.
 3. After enrollment at an engineering college, after each semester submit an official school transcript of your grades to verify eligibility.
 4. A \$1,000.00 scholarship check, per semester up to \$4,000.00 total, will be issued to you upon successful completion of items 1 through 3.
 5. If any of the above rules are not met, then the scholarship will be forfeited.

Requirements

1. Be a high school senior
2. Be a citizen of the United States at the time of application.
3. Have a 3.0 grade point average (based on a 4.0 scale).
4. Attain test scores on the Scholastic Aptitude Test (SAT) or the American College Testing Program (ACT).

Complete the attached application and send it with supporting materials to:

Jeffrey A. Bockhop, P.E.
Stenstrom General Contractor –
Design/Build Group
P. O. Box 5866
Rockford, IL 61125

Deadline: March 15, 2010

Questions may be directed to:

Jeff Bockhop, Rockford Chapter Illinois Society of Professional Engineers, Inc. (815) 398-2420

ISPE/Rockford Chapter Society Scholarship Application (print out)

PERSONAL INFORMATION *(Be sure your name/SS# appears on each page of this application).*

Name: _____
Last First Middle

Home Address: _____
(number/street)

(city/state/zip code)

Phone#: (____) ____-____ E-Mail: _____

Sex: () Male

Date of Birth: __/__/__ SS#: _____

() Female

ACADEMIC INFORMATION

High School: _____ Phone #:(____) ____-____

Cumulative Grade Point Average: _____ (3.0 or higher based on 4.0 grade scale)

SAT or ACT Scores:

SAT: Math (_____)

Verbal (_____)

ACT: Math (_____)

English (_____)

NOTE TO APPLICANT: To be eligible for the scholarship, applicants must attend an engineering program at a university/college that has been accredited by the Engineering Accreditation Commission of the Accreditation Board for Engineering and Technology (ABET-EAC). An applicant may be disqualified if the school it not ABET-EAC accredited.

Schools Applied To: _____

Date Applied: __/__/__

__/__/__

__/__/__

__/__/__

Planned Engineering Major: _____

Name: _____ **SS#:** _____

List on/off campus extracurricular activities during high school, including any position held, such as President,

VOLUNTEER ACTIVITIES: Secretary, etc. Use additional sheet if necessary.

Month/Year to Month Year (most recent first)	Activity	Most Significant Contribution

WORK EXPERIENCE: List employment during school and summer break.

Month/Year to Month Year (most recent first)	Place of Employment Name of Supervisor/Ph. No.	Job Duties/Hours Worked

HONORS AND SCHOLARSHIPS: May or may not be academic-related. Use additional sheet if necessary.

MONTH/YEAR	Sponsor	Name of Award	Reason for Receipt of Award

Name: _____ SS#: _____

How do you plan to finance your education and living

FINANCIAL INFORMATION: expenses for the current school year?

Item	Estimated Cost	Savings	Grants	Scholar-ships	Family Support	Plans you are <i>legally obligated</i> to repay	
tuition/Fees		%	%	%	%	%	= 100%
Books/Supplies		%	%	%	%	%	= 100%
School Year Living Expenses		%	%	%	%	%	= 100%

Do you have any family/financial responsibilities that should be considered when reviewing your application?

(If necessary, use additional sheet)

Please list the name(s)/address(es) of at least two people who will forward mail to you.

Name	Address	Relationship

ESSAY: The essay should discuss your interest in engineering, your major area of study and area of specialization, and the occupation you propose to pursue after graduation. What are your long term goals and how do you hope to achieve them? The essay may also include any other information that is relevant to your career plans. The essay should be a typewritten or computer-printed essay of no more than 500 words, double – spaced. Put your name and major field of engineering at the top of the page.

Assemble the application in the following order. Do not use a report binder.

1. Application
2. Recommendation of Teacher (at least two)
3. Employer Recommendation (optional)
4. Essay (maximum 500 words)

5. Official Transcripts (must be in sealed envelope)

6. SAT/ACT scores (attach official score sheet)

Name: _____ SS#: _____

REQUIRED INFORMATION (Signatures) *Application without required signatures will be disqualified.*

Scholarship Applicant:

I authorize my school officials to give information about my academic records to ISPE/Rockford Chapter.

Yes _____ No _____

To the best of my knowledge, the information presented on this application is complete and true.

(Applicant's Signature) (Date)

Principal/Guidance Counselor Certification:

I certify that the academic information presented on this application is complete and true and that the applicant meets the stated eligibility requirements.

I certify that the applicant is an U.S. citizen.

Signature: _____

Printed Name: _____

Title: _____

High School: _____

Phone#: (____) ____-____

Date: _____

Name: _____ SS# _____